



# YES-G1000

## Manual Plasma Cleaning System

The YES-G1000 is a parallel capacitive plasma system designed to provide the optimum in plasma mode flexibility. For cleaning, stripping, and surface modification, plasma is an effective replacement for toxic chemicals and leaves no solvent residues on surfaces. Byproducts are inert and environmentally safe.

The G1000 is available with 40 kHz and 13.56 MHz, and the user can choose from 5 plasma modes. Anisotropic modes include RIE and active ion trap; isotropic modes include downstream (electron free), active and downstream ion trap.

- RF plasma with 40 kHz and 13.56 MHz
- Low pressure environment
- Downstream to aggressive plasma
- Temperature monitor
- 3 gas inputs
- Gas inputs can include more esoteric gases such as forming gas, CF<sub>4</sub> and SF<sub>6</sub>



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### Applications

- Wirebond cleaning
- Encapsulate cleaning
- Flip chip underfill cleaning
- Contamination removal
- Excellent uniformity and superior control

### Benefits

- Gentle molecular level cleaning
- Clean, repeatable process
- No solvent residues
- Safe and reliable energy

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**Contact Us:** We offer process demonstrations. If you would like to submit samples, please call us. We can run your samples and provide a detailed process report.

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**Yield Engineering Systems, Inc.**

Call: **1-510-954-6889** (worldwide) or **1-888-YES-3637** (US toll free)

[www.yieldengineering.com](http://www.yieldengineering.com)



# G1000 SPECIFICATIONS

For Wire Bond Surface Preparation and Gentle Cleaning Applications

## G1000 SPECIFICATIONS

### HARDWARE

Clean Room Compatibility	Class 10
Operation Temperature	145 °C maximum
N2 Flow Rate	1.7 SCFM
Process Gas Flow Rate	20-50 SCCM average
Interior Chamber Dimensions	45.72 CM (W) X 45.72 CM (D) X 30.48 CM (H) – (18" x 18" x 12")
Chamber Process Area	12 trays total; 13 tray slots for flexible configuration – 15" x 15" shelf size trays for different process modes (Active, ground and floating) – Standard configuration: 4 active, 4 ground, 4 floating
Overall System Dimensions	59.69 cm (W) x 71.12 cm (D) x 113.284 cm (H) – (23.5" x 28" x 44.6")
Chamber Material	6061-T6 aluminum
Process Gas Inputs	3 standard, 4th optional
Mass Flow Controllers	Optional, up to 3 for gas mixing
SEMI™ Compliance	S2/S8

### SOFTWARE

Number of Recipes	12 with load/save/loop/link capability
Range of Exposure Time	0-1200 seconds (20 minutes)
Resolution of Timer Setting	1 second

### PERFORMANCE

RF Plasma Power	0-1000 watts @ 550 VAC, selectable power
RF Leakage Magnetic	0.6 mA/m, 4.15 x 10 <sup>-7</sup> A2/m2 Average
RF Leakage Electrical	1.6 V/m, 4.2 V2/m2 Average
Nitrogen Consumption	0 SCF idle, 6.8 SCF peak, 1.7 SCF average
Power Consumption w/Pump	375W idle, 1000W peak, 640W average
Reactant Gas Consumption	0 SCF idle, 20-50 SCCM
Heat Emission	920 watts average

### ADDITIONAL

Power Requirements	208-230V, 20 amps, 50/60 Hz, 1 phase
System Weight	158.76 kg (350 lbs)

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